

## **Quarterly Reliability Monitoring Results**

## Quarters: Q1/2021 to Q4/2021

Based on structural similarity

| Supplier  |                             | User Part Number  |                       |           |            |           |  |
|---|-----------------------------|---|-----------------------|-----------|------------|-----------|--|
| Nexperia B.V.  Name of Laboratory                 |                             | NZH5V1B Part Description                                    |                       |           |            |           |  |
|   |                             |   |                       |           |            |           |  |
| Assembly reliability labs  Based on AEC-Q101 Test |                             | SMD package   |                       |           |            |           |  |
|   |                             | Test Conditions   | Duration              | # Lots    | # Quantity | # Rejects |  |
|   | TEST                        |   |                       |           |            |           |  |
|   | Pre- and Post-Stress        |   |                       |           |            |           |  |
| # E1  | Electrical Test             | Tamb = 25 °C  | N/A                   | see below | all parts  | see below |  |
|   |                             | JESD22-A113   |                       |           |            |           |  |
|   | PC                          | Bake Tamb = 125 °C<br>Soak Tamb = 85 °C, RH = 85%           | 24 hours<br>168 hours |           |            |           |  |
| # A1  | Preconditioning             | Reflow soldering  | 3 cycles              | 810       | 58300      | 0         |  |
| , //T   |                             | MIL-STD-750-1   | ,                     | 010       | 30300      |           |  |
|   | HTRB                        | M1038 Method A  |                       |           |            |           |  |
|   |                             | Tj = Tjmax, Vr = 100% of max. datasheet                     |                       |           |            |           |  |
| # B1  | Bias                        | reverse voltage   | 1000 hours            | 138       | 11040      | 0         |  |
|   |                             | MIL-STD-750-1   |                       |           |            |           |  |
|   |                             | M1038 Method B  |                       |           |            |           |  |
|   | SSOP                        | Tj = Tjmax, $Iz = 100%$ of max. datasheet                   |                       |           |            |           |  |
| B1b   | Steady State Operational    | reverse current   | 1000 hours            | 20        | 1600       | 0         |  |
|   |                             |   |                       |           |            |           |  |
|   | TC                          | JESD22-A104   |                       |           |            |           |  |
| # A4  | Temperature Cycling         | -65 °C to Tjmax, not to exceed 150°C                        | 1000 cycles           | 170       | 13600      | 0         |  |
|   |                             | JESD22-A102   |                       |           |            |           |  |
|   | <b>AC</b><br>Autoclave      | Tamb = 121 °C, RH = 100 %<br>Pressure = 205 kPa (29.7 psia) | 06.1                  | 170       | 12500      |           |  |
| A3 alt  | Autociave                   | Fressure = 203 KFa (23.7 psia)                              | 96 hours              | 170       | 13600      | 0         |  |
|   | H3TRB                       | IESD22-A101   |                       |           |            |           |  |
|   | High Humidity High          | Tamb = 85 °C, RH = 85%, VR = 80 % of                        |                       |           |            |           |  |
| # A2 alt  |                             | rated reverse voltage <sup>[1]</sup>                        | 1000 hours            | 170       | 13600      | 0         |  |
| ,, ,,,, dic                                       |                             | MIL-STD-750 Method 1037                                     |                       | _, _      | _5000      | -         |  |
|   | IOL                         | ton = toff, devices powered to insure $\Delta T_j$ =        |                       |           |            |           |  |
| # A5  | Intermittent Operating Life |   | 1000 hours            | 170       | 13600      | 0         |  |
|   |                             |   |                       |           |            |           |  |
|   | RSH                         | JESD22-A111   |                       |           |            |           |  |
| ‡ C8  | Resistance to Solder Heat   | 260 °C ± 5 °C   | 10 s                  | 130       | 3900       | 0         |  |
|   | SD                          |   |                       |           |            |           |  |
| # C10   | Solderability               | J-STD-002   |                       | 363       | 3630       | 0         |  |

<sup>[1]</sup> The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|-----------|------------|----------|---------|--------------------|------------|
| Nexperia  |            |          |         |                    |            |
| DHAM      | Zener      | 11040    | 0       | 0.38               | 2.60E+09   |

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